+44 20 8123 2220
info@marketpublishers.com

# Semiconductor Bonding Material Market: Trends, Opportunities and Competitive Analysis [2023-2028]

https://marketpublishers.com/r/S804ACA66B69EN.html
Date: April 2023
Pages: 150
Price: US$ 4,850.00 (Single User License)
ID: S804ACA66B69EN

## Abstracts

Semiconductor Bonding Material Market Trends and Forecast

The future of the global semiconductor bonding material market looks promising with opportunities in the RF device, CMOS image sensor, LED, 3D NAND, and MEMS & sensor applications. The global semiconductor bonding material market is expected to reach an estimated $0.90 billion by 2028 with a CAGR of 8% from 2023 to 2028. The major drivers for this market are rising demand for micro-electromechanical systems, growing preference for electric vehicles, and escalating demand for stacked die technology in IoT (internet of things)-based devices.

A more than 150-page report is developed to help in your business decisions. Sample figures with some insights are shown below.

Semiconductor Bonding Material Market by Segment

The study includes a forecast for the global semiconductor bonding material market by product type, process type, bonding technology, application, and region, as follows:

Semiconductor Bonding Material Market by Product Type [Value ($B) Shipment Analysis from 2017 to 2028]:

- Die Bonder
- Wafer Bonder
- Flip Chip Bonder

+44 20 8123 2220
info@marketpublishers.com

Semiconductor Bonding Material Market by Process Type [Value ($B) Shipment Analysis from 2017 to 2028]:

Die to Die Bonding

Die to Wafer Bonding

Wafer to Wafer Bonding

Semiconductor Bonding Material Market by Bonding Technology [Value ($B) Shipment Analysis from 2017 to 2028]:

Die Bonding Technology

Wafer Bonding Technology

o Wafer Bonding Technology

? Direct and Anodic Wafer Bonding

? Indirect Wafer Bonding

Semiconductor Bonding Material Market by Application [Value ($B) Shipment Analysis from 2017 to 2028]:

RF Devices

CMOS Image Sensors

LED

3D NAND

MEMS and Sensors

Semiconductor Bonding Material Market by Region [Value ($B) Shipment Analysis from 2017 to 2028]:

- North America
- Europe
- Asia Pacific
- The Rest of the World

List of Semiconductor Bonding Material Companies

Companies in the market compete on the basis of product quality offered. Major players in this market focus on expanding their manufacturing facilities, R&D investments, infrastructural development, and leverage integration opportunities across the value chain. With these strategies semiconductor bonding material companies cater increasing demand, ensure competitive effectiveness, develop innovative products & technologies, reduce production costs, and expand their customer base. Some of the semiconductors bonding material companies profiled in this report include.

- ASM Pacific
- BE Semiconductor
- Panasonic
- Fasford
- Shinkawa
- EV Group

Semiconductor Bonding Material Market Insights

- Lucintel forecasts that wafer bonder will remain the largest segment over the forecast period due to increasing application in manufacturing ICs,

microsystems, nanoelectronics, and other micromechanical systems.

LED is expected to remain the largest segment due to expanding usage of semiconductor bonding materials in various applications, such as street lighting, APAC will remain the largest region due to growing production and adoption of electronic products and the presence some of the largest semiconductor companies in countries like China, India, and Vietnam.

Features of the Semiconductor Bonding Material Market

Market Size Estimates: Semiconductor bonding material market size estimation in terms of value ($B)

Trend And Forecast Analysis: Market trends (2017-2022) and forecast (2023-2028) by various segments and regions.

Segmentation Analysis: Semiconductor bonding material market size by various segments, such as by product type, process type, bonding technology, application, and region

Regional Analysis: Semiconductor bonding material market breakdown by North America, Europe, Asia Pacific, and the Rest of the World.

Growth Opportunities: Analysis on growth opportunities in different by product type, process type, bonding technology, application, and regions for the semiconductor bonding material market.

Strategic Analysis: This includes M&A, new product development, and competitive landscape for the semiconductor bonding material market.

Analysis of competitive intensity of the industry based on Porter's Five Forces model.

FAQ

Q1. What is the semiconductor bonding material market size?

Answer: The global semiconductor bonding material market is expected to reach an estimated $0.90 billion by 2028.

Q2. What is the growth forecast for semiconductor bonding material market?

Answer: The global semiconductor bonding material market is expected to grow with a CAGR of 8% from 2023 to 2028.

Q3. What are the major drivers influencing the growth of the semiconductor bonding material market?

Answer: The major drivers for this market are rising demand for micro-electromechanical systems, growing preference for electric vehicles, and escalating demand for stacked die technology in IoT (internet of things)-based devices.

Q4. What are the major segments for semiconductor bonding material market?

Answer: The future of the semiconductor bonding material market looks promising with opportunities in the RF device, CMOS image sensor, LED, 3D NAND, and MEMS & sensor applications.

Q5. Who are the key semiconductor bonding material companies?

Answer: Some of the key semiconductors bonding material companies are as follows:

- ASM Pacific
- BE Semiconductor
- Panasonic
- Fasford
- Shinkawa
- EV Group

Q6. Which semiconductor bonding material segment will be the largest in future?

Answer:Lucintel forecasts that wafer bonder will remain the largest segment over the forecast period due to increasing application in manufacturing ICs, microsystems, nanoelectronics, and other micromechanical systems.

Q7. In semiconductor bonding material market, which region is expected to be the largest in next 5 years?

Answer: APAC will remain the largest region due to growing production and adoption of electronic products and the presence some of the largest semiconductor companies in countries like China, India, and Vietnam.

Q8. Do we receive customization in this report?

Answer: Yes, Lucintel provides 10% Customization Without any Additional Cost.

This report answers following 11 key questions

Q.1. What are some of the most promising, high-growth opportunities for the semiconductor bonding material market by product type (die bonder, wafer bonder, and flip chip bonder), process type (die to die bonding, die to wafer bonding, and wafer to wafer bonding), bonding technology (die bonding technology and wafer bonding technology), application (RF devices, CMOS image sensors, LED, 3D NAND, and MEMS & sensors), and region (North America, Europe, Asia Pacific, and the Rest of the World)?
Q.2. Which segments will grow at a faster pace and why?
Q.3. Which region will grow at a faster pace and why?
Q.4. What are the key factors affecting market dynamics? What are the key challenges and business risks in this market?
Q.5. What are the business risks and competitive threats in this market?
Q.6. What are the emerging trends in this market and the reasons behind them?
Q.7. What are some of the changing demands of customers in the market?
Q.8. What are the new developments in the market? Which companies are leading these developments?
Q.9. Who are the major players in this market? What strategic initiatives are key players pursuing for business growth?
Q.10. What are some of the competing products in this market and how big of a threat do they pose for loss of market share by material or product substitution?
Q.11. What M&A activity has occurred in the last five years and what has its impact

been on the industry?

For any questions related to semiconductor bonding material market or related semiconductor bonding material companies, semiconductor bonding material market size, semiconductor bonding material market share, semiconductor bonding material analysis, write Lucintel analyst at email: helpdesk@lucintel.com we will be glad to get back to you soon.

## Contents

**1. EXECUTIVE SUMMARY**

**2. GLOBAL SEMICONDUCTOR BONDING MATERIAL MARKET: MARKET DYNAMICS**

2.1: Introduction, Background, and Classifications
2.2: Supply Chain
2.3: Industry Drivers and Challenges

**3. MARKET TRENDS AND FORECAST ANALYSIS FROM 2017 TO 2028**

3.1: Macroeconomic Trends (2017-2022) and Forecast (2023-2028)
3.2: Global Semiconductor Bonding Material Market Trends (2017-2022) and Forecast (2023-2028)
3.3: Global Semiconductor Bonding Material Market by Product Type
  3.3.1: Die Bonder
  3.3.2: Wafer Bonder
  3.3.3 Flip Chip Bonder
3.4: Global Semiconductor Bonding Material Market by Process Type
  3.4.1: Die to Die Bonding
  3.4.2: Die to Wafer Bonding
  3.4.3: Wafer to Wafer Bonding
3.5: Global Semiconductor Bonding Material Market by Bonding Technology
  3.5.1: Die Bonding Technology
  3.5.2: Wafer Bonding Technology
    3.5.2.1: Wafer Bonding Technology
      3.5.2.1.1: Direct and Anodic Wafer Bonding
      3.5.2.1.2: Indirect Wafer Bonding
3.6: Global Semiconductor Bonding Material Market by Application
  3.6.1: RF Devices
  3.6.2: CMOS Image Sensors
  3.6.3: LED
  3.6.4: 3D NAND
  3.6.5: MEMS and Sensors

**4. MARKET TRENDS AND FORECAST ANALYSIS BY REGION FROM 2017 TO 2028**

4.1: Global Semiconductor Bonding Material Market by Region
4.2: North American Semiconductor Bonding Material Market
  4.2.1: North American Semiconductor Bonding Material Market by Product Type: Die Bonder, Wafer Bonder, and Flip Chip Bonder
  4.2.2: North American Semiconductor Bonding Material Market by Application: RF Devices, CMOS Image Sensors, LED, 3D NAND, and MEMS & Sensors
4.3: European Semiconductor Bonding Material Market
  4.3.1: European Semiconductor Bonding Material Market by Product Type: Die Bonder, Wafer Bonder, and Flip Chip Bonder
  4.3.2: European Semiconductor Bonding Material Market by Application: RF Devices, CMOS Image Sensors, LED, 3D NAND, and MEMS & Sensors
4.4: APAC Semiconductor Bonding Material Market
  4.4.1: APAC Semiconductor Bonding Material Market by Product Type: Die Bonder, Wafer Bonder, and Flip Chip Bonder
  4.4.2: APAC Semiconductor Bonding Material Market by Application: RF Devices, CMOS Image Sensors, LED, 3D NAND, and MEMS & Sensors
4.5: ROW Semiconductor Bonding Material Market
  4.5.1: ROW Semiconductor Bonding Material Market by Product Type: Die Bonder, Wafer Bonder, and Flip Chip Bonder
  4.5.2: ROW Semiconductor Bonding Material Market by Application: RF Devices, CMOS Image Sensors, LED, 3D NAND, and MEMS & Sensors

**5. COMPETITOR ANALYSIS**

5.1: Product Portfolio Analysis
5.2: Operational Integration
5.3: Porter's Five Forces Analysis

**6. GROWTH OPPORTUNITIES AND STRATEGIC ANALYSIS**

6.1: Growth Opportunity Analysis
  6.1.1: Growth Opportunities for the Global Semiconductor Bonding Material Market by Product Type
  6.1.2: Growth Opportunities for the Global Semiconductor Bonding Material Market by Process Type
  6.1.3: Growth Opportunities for the Global Semiconductor Bonding Material Market by Bonding Technology
  6.1.4: Growth Opportunities for the Global Semiconductor Bonding Material Market by

+44 20 8123 2220
info@marketpublishers.com

Application
6.1.5: Growth Opportunities for the Global Semiconductor Bonding Material Market by Region
6.2: Emerging Trends in the Global Semiconductor Bonding Material Market
6.3: Strategic Analysis
6.3.1: New Product Development
6.3.2: Capacity Expansion of the Global Semiconductor Bonding Material Market
6.3.3: Mergers, Acquisitions, and Joint Ventures in the Global Semiconductor Bonding Material Market
6.3.4: Certification and Licensing

## 7. COMPANY PROFILES OF LEADING PLAYERS

7.1: ASM Pacific
7.2: BE Semiconductor
7.3: Panasonic
7.4: Fasford
7.5: Shinkawa
7.6: EV Group

+44 20 8123 2220
info@marketpublishers.com

## I would like to order

Product name: Semiconductor Bonding Material Market: Trends, Opportunities and Competitive Analysis [2023-2028]

Product link: https://marketpublishers.com/r/S804ACA66B69EN.html

Price: US$ 4,850.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:

info@marketpublishers.com

## Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page https://marketpublishers.com/r/S804ACA66B69EN.html

## To pay by Wire Transfer, please, fill in your contact details in the form below:

First name:

Last name:

Email:

Company:

Address:

City:

Zip code:

Country:

Tel:

Fax:

Your message:

**All fields are required

Custumer signature _______________________________________

Please, note that by ordering from marketpublishers.com you are agreeing to our Terms & Conditions at https://marketpublishers.com/docs/terms.html

To place an order via fax simply print this form, fill in the information below and fax the completed form to +44 20 7900 3970

+44 20 8123 2220
info@marketpublishers.com